Technical data sheet

Product:	108
Manufacturer:	HENKEL KGAA
Product group:	KLEBSTOFF
Article group:	1-K KLEBSTOFF
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LOCTITE® ESP 108

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LOCTITE® ESP108

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Description:

Loctite ESP108 is a paste adhesive which flows like solder when cured. It is designed to provide maximum resistance to impact, shear, cleavage and tensile loads. The durability, chemical resistance and high temperature performance are extremely good. ESP108 will bond to a wide variety of surfaces, including oily steel, and performance is usually limited by the strength of the adherends themselves. In many applications it can replace traditional fixing techniques to give enhanced appearance and greater design flexibility.

Physical Properties

Colour	Silver
Viscosity (mPa.s)	170,000
Specific Gravity	1.5

Storage:

When stored in the original unopened containers at 5-7°C, the shelf life of this product is 12 months from the date of manufacture.

Typical Performance	
Shear Strength (MPa) - Steel*	30
Coeff. of Thermal Expansion (mm/mm/°C)	45 x 10^{-6}
Maximum Gap Fill (mm)	< 0.5

Service Temperature:

The recommended service temperature range for this product is -40 to +180°C. However higher temperatures may be endured for short periods providing the adhesive is not unduly stressed.

With joints involving materials such as ferrites or SMC bond strengths are generally greater than that of the substrate itself. The bond strengths measured on the be affected by the modulus of the metal and the thickness of the actual components.

Handling:

Full information can be obtained from the Material Safety Data Sheet (MSDS). Users are reminded that all materials, whether innocuous or not, should be handled according to the principles of good industrial hygiene more ductile metals, such as copper and its alloys, will

Cure Time at:-	**100°C**	**120°C**	**150°C**	**180°C**
Minutes* (in an air circulating oven)	240	60	45	20

*The actual cure time for any application is dependent on the time it takes for the adhesive to reach temperature. Larger components, or batch curing, will require a longer warm up time and the cure cycle may be extended. The use of alternative heating methods may also affect the time required to achieve full cure; Hotplates, Infra-Red lamps or Induction heating will generally give a faster cure.

Directions for Use:

Surfaces should be clean, dry and grease free before applying the adhesive. Where ultimate performance is required then the surfaces should be shot blasted, or lightly abraded, in the presence of **Loctite SIP.**

The adhesive should be extruded using a bead diameter that will allow complete coverage of the bond area. Care should be taken not to include, or trap, any air within the joint. Normally it should be applied to only one surface.

Assemble the parts and squeeze together with sufficient pressure to ensure the adhesive spreads to cover the entire Loctite ESP108 is approved to the Waters Byelaws Scheme as being suitable for contact with potable (drinking) bond area. Jig the components using a light clamping pressure and place in the oven to cure. Do not disturb the joint water until the adhesive has cured.